

S62	3	("4310236").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2003/01/08 13:44
S63	507	(400/625.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/30 16:10
S64	1261	(400/624,578.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:30
S65	956	(400/636,271,226.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:31
S66	101	S63 and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane paper sheet web medium media) with (back\$1lash return\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 08:35
S67	171	S64 and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane paper sheet web medium media) with (back\$1lash return\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:36

S68	125	S65 and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane paper sheet web medium media) with (back\$1lash return\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:36
S69	5	S63 and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane paper sheet web medium media) with back\$1lash	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:36
S70	10	S64 and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane paper sheet web medium media) with back\$1lash	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:43
S71	19	S65 and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane paper sheet web medium media) with back\$1lash	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 16:49
S72	56	(back\$1lash return\$3) adj (reduc\$5 demot\$5 decreas\$5) adj (assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment cell appliance structure) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 12:43
S73	7	S72 and (convey\$4 feed\$4 advanc\$4 transfer\$4 rotat\$4 roll\$4) same (media medium paper sheet substrate material \$5film coat\$3 layer pad wafer lamina level plane web) same (position location region zone co\$1 ordinat\$5 segment section part portion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 09:52

S74	2	S72 and (convey\$4 feed\$4 advanc\$4 transfer\$4 deliver\$4 rotat\$4) with ((final second target prc\$1 select\$3 pre\$1 determin\$3 spec\$1 defin\$3 spec\$1 set\$4) adj2 (position location region zone co\$1 lordinat\$5 segment section part portion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 09:47
S75	414	(back\$1 lash return\$3) adj (reduc\$5 demot\$5 decreas\$5 prevent\$5 eliminat\$5 avoid\$5) adj (assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment cell appliance structure) and @add<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 09:33
S76	36	S75 and (convey\$4 feed\$4 advanc\$4 transfer\$4 deliver\$4 rotat\$4) with ((final second target prc\$1 select\$3 pre\$1 determin\$3 spec\$1 defin\$3 spec\$1 set\$4) adj2 (position location region zone co\$1 lordinat\$5 segment section part portion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 09:49
S77	36	S75 and (convey\$4 feed\$4 advanc\$4 transfer\$4 deliver\$4 rotat\$4) with ((final second target prc\$1 select\$3 pre\$1 determin\$3 spec\$1 defin\$3 spec\$1 set\$4) adj2 (intend\$5) adj2 (position location region zone co\$1 lordinat\$5 segment section part portion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 09:53
S78	1217033	(convey\$4 feed\$4 advanc\$4 transfer\$4 deliver\$4 rotat\$4) near3 (media medium paper sheet substrate material \$5film coat\$3 layer pad wafer lamina level web) and @add<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 09:57
S79	263211	S78 and (stop\$5 ceas\$5 end\$3 hal\$5 hold\$3 paus\$3) near3 (media medium paper sheet substrate material \$5film coat\$3 layer pad wafer lamina level web)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 10:16

S80	45172	S79 and (media medium paper sheet substrate material \$5film coat\$3 layer pad wafer lamina level plane web) with ((final second target pre\$1select\$3 pre\$1determin\$3 pre\$1defin\$3 specif\$5 pre\$1set\$4) adj2 (position location region zone co\$1ordinat\$5 segment section part portion))	US-PGPUB; USPAT; USOOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 10:36
S81	26915	S80 and (media medium paper sheet substrate material \$5film coat\$3 layer pad wafer lamina level plane web) near3 ((final second target pre\$1select\$3 pre\$1determin\$3 pre\$1defin\$3 specif\$5 pre\$1set\$4) adj2 (position location region zone co\$1ordinat\$5 segment section part portion))	US-PGPUB; USPAT; USOOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 10:26
S82	956	S81 and (reduc\$5 demot\$5 decrease\$5 prevent\$5 eliminat\$5 avoid\$5 \$2adjust\$5 regulat\$3 control\$3 calibrat\$5) near2 (back\$1lash return\$3)	US-PGPUB; USPAT; USOOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 10:31
S83	83	S82 and short near3 (position location region zone co\$1ordinat\$5 segment section part portion)	US-PGPUB; USPAT; USOOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 10:39
S84	0	S83 and back\$1lash adj (reduc\$5 demot\$5 decrease\$5)	US-PGPUB; USPAT; USOOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/28 13:09
S85	2	S83 and back\$1lash adj (reduc\$5 demot\$5 decrease\$5 prevent\$5 eliminat\$5 avoid\$5 \$2adjust\$5 regulat\$3 control\$4 calibrat\$5)	US-PGPUB; USPAT; USOOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/30 16:19

S86	2	("5961224").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	OFF	2005/09/28 16:20
S87	12	((back\$1lash and (reduc\$5 demot\$5 decreas\$5 prevent\$5 eliminat\$5 avoid\$5 \$2adjust\$5 regulat\$3 control\$4 calibrat\$5) and short and (position location region zone co\$1ordinat\$5 segment section part portion) and (media medium paper sheet substrate material \$5film coat\$3 layer pad wafer lamina level plane web) and (final second target pre\$1select\$3 pre\$1determin\$3 pres\$1defin\$3 speci\$5 pre\$1set\$4) and (convey\$4 feed\$4 advanc\$4 transfer\$4 deliver\$4 rotat\$4 roll\$4)).clm.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 15:56
S88	1363	(400/582,593,608,4.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:11
S89	1539	(400/621,629,630,637,636,2.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:15
S90	1569	(271/10,05,227,258,01,270,242.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:16
S91	1730	(101/116,118,216,226,232.cccls.) and @ad<"20010801"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:17

S92	7	S88 and back\$1 lash near3 (reduc\$\$5 demot\$\$5 decreas\$\$5 prevent\$\$5 avoid\$\$5 \$2adjust\$ regulat\$\$3 control\$\$4 calibrat\$\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:26
S93	6	S89 and back\$1 lash near3 (reduc\$\$5 demot\$\$5 decreas\$\$5 prevent\$\$5 avoid\$\$5 \$2adjust\$ regulat\$\$3 control\$\$4 calibrat\$\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:33
S94	8	S90 and back\$1 lash near3 (reduc\$\$5 demot\$\$5 decreas\$\$5 prevent\$\$5 avoid\$\$5 \$2adjust\$ regulat\$\$3 control\$\$4 calibrat\$\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT ; IBM_TDB	OR	ON	2005/09/30 16:34